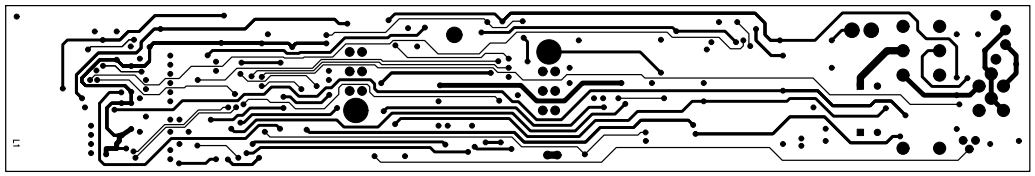
RIGHT READING WHEN VIEWED FROM LAYER 1 - TOP

COVIDIEN

Powerpack2 Board, 10106054 Rev A

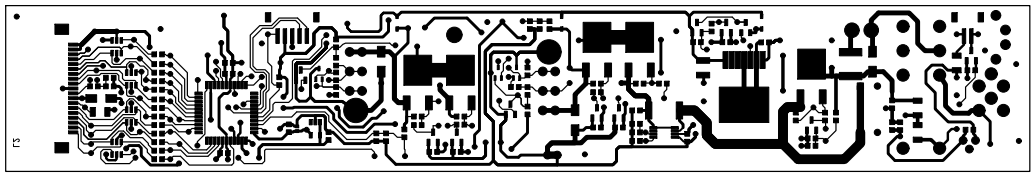


LAYER 1 - PRIMARY SIDE

RIGHT READING WHEN VIEWED FROM LAYER 1 - TOP

COVIDIEN

Powerpack2 Board, 10106054 Rev A



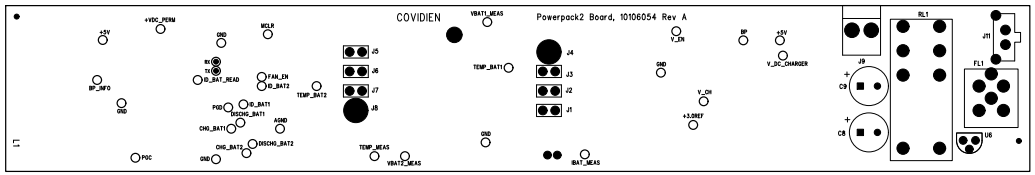
Y
X

LAYER 2 - SECONDARY SIDE

RIGHT READING WHEN VIEWED FROM LAYER 1 - TOP

COVIDIEN

Powerpack2 Board, 10106054 Rev A



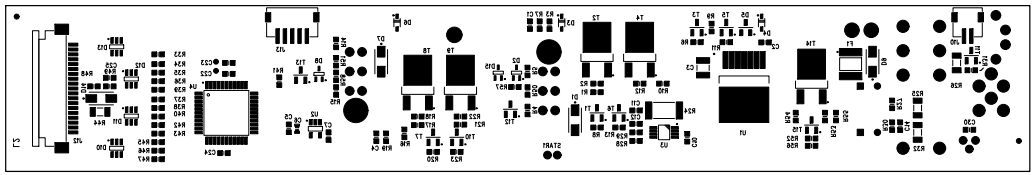
LAYER 1 - PRIMARY SIDE

SILKSCREEN TOP

RIGHT READING WHEN VIEWED FROM LAYER 1 - TOP

COVIDIEN

Powerpack2 Board, 10106054 Rev A



LAYER 2 - SECONDARY SIDE

SILKSCREEN BOTTOM

RIGHT READING WHEN VIEWED FROM LAYER 1 - TOP

COVIDIEN

Powerpack2 Board, 10106054 Rev A

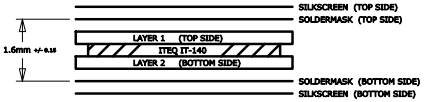
NOTES: UNLESS OTHERWISE SPECIFIED.

1. APPLICABLE STANDARDS/SPECIFICATIONS:
   ASME Y14.3- 2008, MULTIVIEW AND SECTIONAL VIEW DRAWINGS.
   ASME Y14.4M-2009, PICTORIAL DRAWINGS.
   ASME Y14.5-2009, DIMENSIONS AND TOLERANCES.
   ASME Y14.38-2007, ABBREVIATIONS AND ACRONYMS.
   ALL SPECIFICATIONS REFERENCED SHALL BE OF THE LATEST REVISIONS.
2. ALL DIMENSIONS IN MM.
3. FABRICATE IN ACCORDANCE WITH IPC-6012 TYPE 3 PER IPC-6011 CLASS 3 MINIMUM DIELECTRIC ACCEPTABLE TO BE 0.050 (.002).
4. MATERIAL: COPPER CLAD LAMINATES ISOLA 370HR (OR EQUIVALENT), RoHS COMPLIANT. U.L. DESIGNATION: ANSI GRADE FR-4, PER IPC 4101. COPPER WEIGHT SHALL BE 1/2 OZ. PLATED TO 1 OZ. ON EXTERNAL LAYERS AND 1 OZ. ON INTERNAL LAYERS. OVERALL BOARD THICKNESS TO BE 1.6MM 10%..BOARD PROFILE TOLERANCE TO BE 0.2MM. COPPER PLATE ON WALLS OF HOLES SHALL BE .001 AVERAGE, .0008 ABSOLUTE MINIMUM. ENIG FINISH AND FOLLOW IPC-4552 TO BUILD.
5. GERBER DATA MUST BE VERIFIED AGAINST THE IPC-356A NETLIST BEFORE FABRICATION.
6. MINIMUM CONDUCTOR WIDTHS OF 0.100 (0.004) AND SPACINGS OF 0.100 (0.004) SHALL BE HELD WITHIN +/- 20% OF ORIGINAL DATA.
7. ALL SMD PAD PLATING TO BE FLAT TO A MAX. OF 0.080 (0.003) ABOVE BOARD SURFACE.
8. USE GREEN LIQUID PHOTO IMAGEABLE SOLDER MASK CONFORMING TO IPC-SM-840, CLASS H. BOARD TO HAVE SOLDER MASK OVER BARE COPPER ON BOTH SIDES. NO SOLDERMASK TO PAD PERMISSIBLE, EXCEPT VIAS.
9. ALL EXPOSED CONDUCTIVE SURFACES TO BE IMMERSION NICKEL/GOLD PLATING USING 100-400 MICROINCHES NICKEL AND 2-5 MICROINCHES GOLD.
10. WARP OR TWIST OF BOARD SHALL NOT EXCEED 0.75%.
11. SILKSCREEN BOTH SIDES USING WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE EPOXY INK. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PADS.
12. REMOVE ALL BURRS AND BREAK SHARP EDGES 0.400 (0.015) MAX.
13. FINISHED BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0. VENDOR'S UL LOGO, DATE CODE AND LOT IDENTIFICATION SHALL BE LOCATED ON THE TOP SIDE OF THE BOARD IN ETCH. SILKSCREEN ACCEPTABLE.
14. ALL BOARDS TO BE 100% ELECTRICALLY TESTED USING AN IPC-356A NETLIST. ALL NETS TO BE CHECKED FOR CONTINUITY AND SHORTS.
15. TEST DATA AND CERTIFICATE OF COMPLIANCE TO BE SUPPLIED WITH EACH BATCH OF BOARDS.
16. MINIMUM ANNULAR RING IS .001. TANGENCY IS PERMITTED ON .036 AND .009 DRILL HOLES.
17. LAYER REGISTRATION TO BE <0.004"
18. ENSURE ALL UPDATES TO THE GERBER FILES ARE INCORPORATED INTO THE FABRICATION DRAWING P/N 10106054 AS NECESSARY.
19. PART/COMPONENT TO BE RoHS COMPLIANT

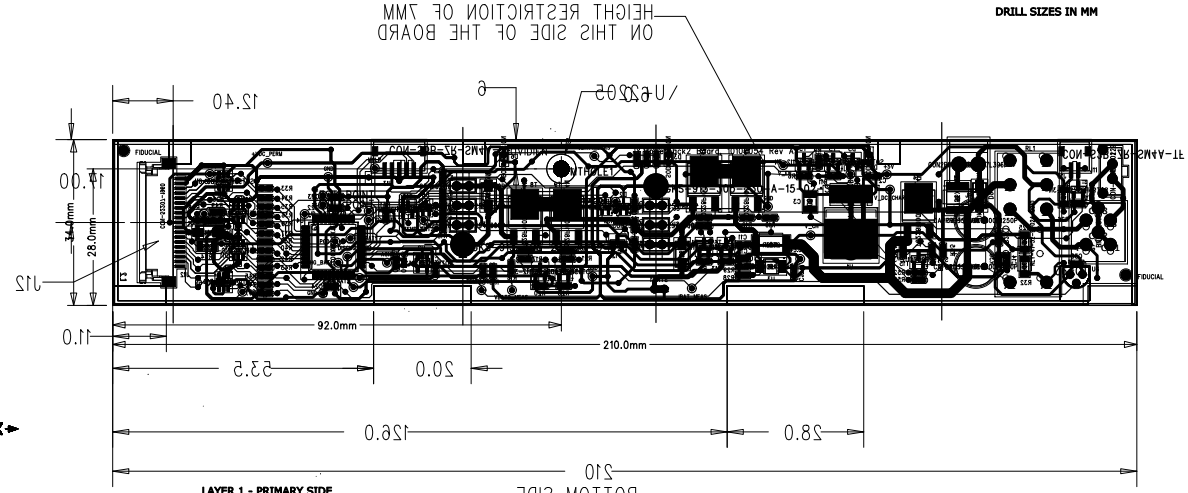
DRILL TABLE

SIZE	QTY	SYM	PLATED	TOL
0.4	183	+	YES	+/-0.127
1	19	X	YES	+/-0.127
0.8	4	□	YES	+/-0.127
1.3	16	◇	YES	+/-0.127
3	2	⧖	YES	+/-0.127
3.18	1	⋈	NO	+/-0.05
1.7	2	⊥	YES	+/-0.127

LAYUP DETAIL
2 LAYER



DRILL SIZES IN MM



LAYER 4 – BOTTOM

LAYER 1 - PRIMARY SIDE
LAYER 2 - SECONDARY SIDE
SILKSCREEN TOP
SILKSCREEN BOTTOM
RESIST TOP
RESIST BOTTOM
PASTE TOP
PASTE BOTTOM
MANUFACTURING